# Guest editorial

## IMAPS 2019 Poland

The International Microelectronics and Packaging Society (IMAPS) Poland Chapter was established in September 1982. In the beginning, it was the ISHM-Poland Chapter and from the 1997 it became the IMAPS-Poland Chapter.

The IMAPS is a non-profit making organization whose aim is to spread of knowledge relating to hybrid microelectronics; a key technology in the assembly and application of semiconductors, thin film circuits and printed circuit boards to form practical miniaturized electronic equipment. In 2008, the IMAPS joined with IEEE components, packaging and manufacturing technology (CPMT) society, bringing into formation the IMAPS-CPMT organization.

The 43rd IMAPS Poland International Conference was joined with 13th ELTE 2019 Conference and it was organized by Wroclaw University of Technology. This joined event took place between 4 and 6 September 2019. The scope of the conference covered everything in electronics between the chip and the system. Both conferences were attended by 102 participants, including 9 guests from abroad. During the conference, 17 invited lectures, 25 regular lectures and 54 posters were presented. The conference was supported by four international journals indexed in Journal Citation Report database and two journals indexed in Scopus.

This year, as in the previous year, two young Scientists have been awarded winning the refund of the conference fee during the next IMAPS 2019 Poland Conference.

In the special issue of *Soldering and Surface Mount Technology*, eight papers have been collected. All of them were subjected to the journal's regular reviewing procedure.

First papers by Górecki *et al.* and Dziurdzia *et al.* are related to the influence of soldering methods and pastes on chosen parameters of LED assemblies. In the next paper, Krammer *et al.* deal with numerical investigation of solder paste rheological behavior during stencil printing. Yahaya *et al.* describe the results of selective etching of SAC305 solder joints. Paper of Kiliszkiewicz *et al.* treats the inkjet-printed capacitor fabrication and paper of Stojek *et al.* the thermographic analysis of silver-based thermal joints. The last two papers, by Straubinger *et al.* and Alaya *et al.*, report about different aspects of vapor phase soldering.

I would like to thank all the authors for their scientific work and contributions that have led to the development and publication of this special issue of *Soldering and Surface Mount Technology*. I hope that it will be of interest to readers of the journal and that it will help them to find novel solutions, contribute to the creation of new ideas and initiate many varied discussions about different technologies and problems related to microelectronics issues. I believe that this branch of science could be effectively developed in the future.

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